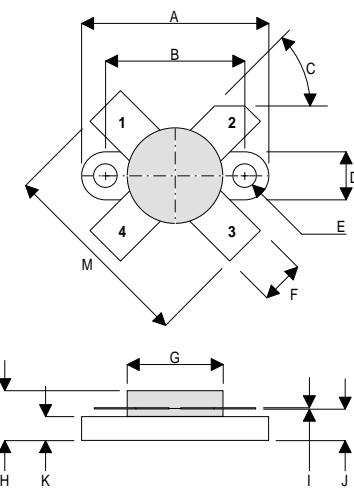


MECHANICAL DATA



DMX

PIN 1	SOURCE	PIN 2	DRAIN
PIN 3	SOURCE	PIN 4	GATE

DIM	mm	Tol.	Inches	Tol.
A	28.83	0.13	1.135	0.005
B	21.97	0.13	0.865	0.005
C	45°	5°	45°	5°
D	6.86	0.13	0.27	0.005
E	3.43 Dia.	0.13	0.135 Dia.	0.005
F	5.84	0.13	0.230	0.005
G	13.97 Dia.	0.13	0.550 Dia.	0.005
H	6.60	REF	0.260	REF
I	0.13	0.02	0.005	0.001
J	3.81	0.25	0.15	0.01
K	2.54	0.13	0.100	0.005
M	27.94	0.51	1.10	0.02

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^\circ\text{C}$ unless otherwise stated)

P_D	Power Dissipation	500W
BV_{DSS}	Drain – Source Breakdown Voltage	125V
BV_{GSS}	Gate – Source Breakdown Voltage	$\pm 20\text{V}$
$I_{D(sat)}$	Drain Current	36A
T_{stg}	Storage Temperature	-65 to 150°C
T_j	Maximum Operating Junction Temperature	200°C

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^\circ C$ unless otherwise stated)

Parameter	Test Conditions		Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0$	$I_D = 100mA$	125		V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 50V$	$V_{GS} = 0$		12	mA
I_{GSS}	Gate Leakage Current	$V_{GS} = 20V$	$V_{DS} = 0$		12	μA
$V_{GS(th)}$	Gate Threshold Voltage*	$I_D = 10mA$	$V_{DS} = V_{GS}$	1	7	V
g_{fs}	Forward Transconductance*	$V_{DS} = 10V$	$I_D = 6A$	9.6		S
G_{PS}	Common Source Power Gain	$P_O = 300W$		20		dB
η	Drain Efficiency	$V_{DS} = 50V$	$I_{DQ} = 1.2A$	50		%
VSWR	Load Mismatch Tolerance	$f = 30MHz$		20:1		—
C_{iss}	Input Capacitance	$V_{DS} = 50V$	$V_{GS} = -5V$		720	pF
C_{oss}	Output Capacitance	$V_{DS} = 50V$	$V_{GS} = 0$		300	pF
C_{rss}	Reverse Transfer Capacitance	$V_{DS} = 50V$	$V_{GS} = 0$		18	pF

* Pulse Test: Pulse Duration = 300 μs , Duty Cycle $\leq 2\%$

HAZARDOUS MATERIAL WARNING

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area.

THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

THERMAL DATA

$R_{THj-case}$	Thermal Resistance Junction – Case	Max. 0.35°C / W
----------------	------------------------------------	-----------------

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.